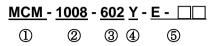
I. SCOPE:

This specification applies to the Pb Free high current type SMD Common mode filter

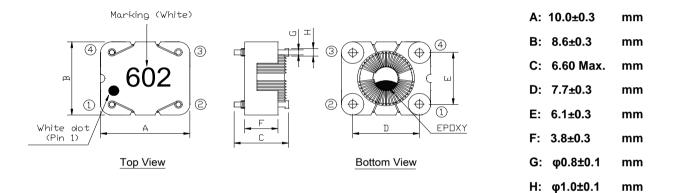
for MCM-1008-SERIES-

PRODUCT INDENTIFICATION



- ① Product Code
- ② Dimensions Code
- **③ Inductance Code**
- **④** Tolerance Code
- **⑤ Inner Control Code**

(1) SHAPES AND DIMENSIONS



(2) ELECTRICAL SPECIFICATIONS SEE TABLE 1

TEST INSTRUMENTS

- L : HP 4284A PRECISION LCR METER (or equivalent)
- RDC : CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)
- I.R : CHROMA MODEL 19073 AC/DC/IR HIPOT TESTER (or equivalent)

(3) CHARACTERISTICS

(3)-1 Operate temperature range -40° C \sim $+125^{\circ}$ C

(Including self temp. rise)

(3)-2 Storage temperature range -40° C ~ $+125^{\circ}$ C

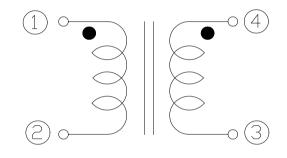


TABLE 1

	Inductance	L Test	Resistance	Rated	Rated	
MAGLAYERS PT/NO.	L(uH)	_	RDC(Ω) Max.	current	voltage	Marking
	(1-2),(4-3)	Frequency	(1 line)	DC (A)max.	DC (V) max.	
MCM-1008-251Y-E-	250±40%	100KHz/0.1V	35m	2.00	80	● ²⁵¹
MCM-1008-122Y-E-	1200 +50%/-30%	1KHz/0.25V	124m	1.80	80	● ¹²²
MCM-1008-222Y-F-	2200±40%	100KHz/0.1V	0.20	1.10	80	● ²²²
MCM-1008-392Y-H-	3900±40%	100KHz/0.1V	0.54	0.52	80	● ³⁹²
MCM-1008-602Y-E-	6000±40%	10KHz/0.1V	0.87	0.55	80	● 602

Rated current : Based on temperature rise ($\triangle T : 40^{\circ}C$ TYP.)

CIRCUIT DIAGRAM





(4) RELIABILITY TEST METHOD

MAG.LAYERS

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS	
Solder ability	The product shall be connected to the test	Apply cream solder to the printed circuit board .	
	circuit board by the fillet (the height is 0.2mm).	Refer to clause 8 for Reflow profile.	
Resistance to	There shall be no damage or problems.	Temperature profile of reflow soldering	
Soldering heat		⊖ 300- soldering (Peak temperature 260±3°C 10	
(reflow soldering)		Pre-heating 250 200 150 150 2 min 2 mi	
		shall be made.	
Terminal strength	The terminal electrode and the ferrite must not damaged.	Solder a chip to test substrate , and then laterally apply a load 9.8N in the arrow direction.	
		Primed circuit board \$01.0	
Strength on PC boa	The terminal electrode and the ferrite must	Solder a chip to test substrate and then apply a load.	
bending	not damaged.	Test board:FR4 100×40×1mm R10 Fall speed:1mm/sec. 45 45 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5	
High	Inductance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit	
temperature	Insulation resistance and DC resistance on the	board,the test shall be done.	
resistance	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.	
	The terminal electrode and the ferrite must not	•	
	damaged.	Applied voltage : Rated voltage	
		Applied current : Rated current	
		Testing time : 500±12 hours	



(4) RELIABILITY TEST METHOD

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS
Humidity	Inductance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit
resistance	Insulation resistance and DC resistance on the	board,the test shall be done.
	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.
	The terminal electrode and the ferrite must not	Temperature : +60±2 $^\circ\!\!{\rm C}$, Humidity : 90 to 95 %RH
	damaged.	Applied voltage : Rated voltage
		Applied current : Rated current
		Testing time : 500±12 hours
Thermal shock	Inductance:Within±20% of the initial value.	$\leftarrow 1 \text{ cycle}$
	Insulation resistance and DC resistance on the	$+125^{\circ}$ C 30 min
	specification(refer to clause 2-1) shall be met.	
	The terminal electrode and the ferrite must	
	not damaged.	-40° C + 30° min.
		Testing time:100 cycle
Low	Inductance:Within±20% of the initial value.	After the samples shall be soldered onto the test
temperature	Insulation resistance and DC resistance on the	circuit board,the test shall be done.
storage	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.
	The terminal electrode and the ferrite must	Temperature : -40±2℃
	not damaged.	Testing time : 500±12 hours
Vibration	Inductance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit
	Insulation resistance and DC resistance on	board,the test shall be done.
	the specification(refer to clause 2-1)	Frequency : 10 to 55 Hz
	shall be met.	Amplitude : 1.52 mm
	The terminal electrode and the ferrite must	Dimension and times : X ,Y and Z directions
	not damaged.	for 2 hours each.
Soldorobility	New solder More than 75%	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated
Solderability		over the whole of the sample before hard, the sample shall
		then be preheated for about 2 minutes in a temperature
		of $130 \sim 150^{\circ}$ and after it has been immersed to a depth
		0.5mm below for 3±0.2 seconds fully in molten solder
		M705 with a temperature of $245\pm2^{\circ}$. More than 75% of the
		electrode sections shall be couered
		with new solder smoothly when the sample is taken out
		of the solder bath.



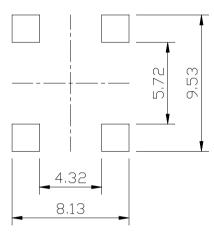
MAG.LAYERS

(5) LAND DIMENSION (Ref.)

PCB: GLASS EPOXY t=1.6mm

(5)-1 LAND PATTERN DIMENSIONS

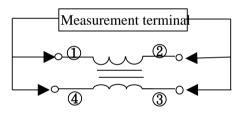
(STANDARD PATTERN)



(6) TEST EQUIPMENT

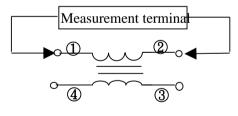
(6)-1 Inductance

Measured by using HP4284A RF LCR meter.



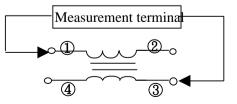
(6)-2 DC Resistance

Measured by using Chroma 16502 milliohm meter.



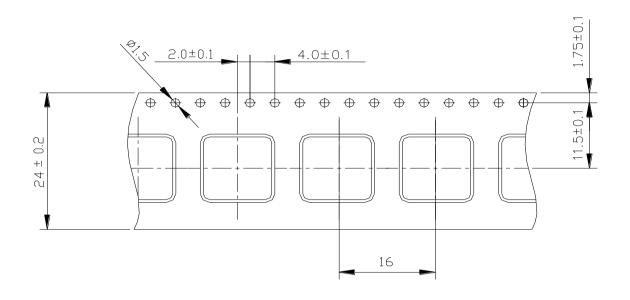
(6)-3 Insulation Resistance

Measured by using Chroma 19073

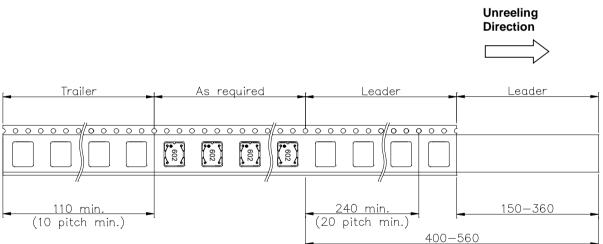




(7) PACKAGING (7)-1 CARRIER TAPE DIMENSIONS (mm)

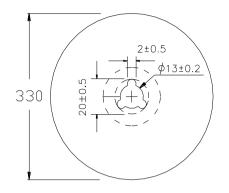


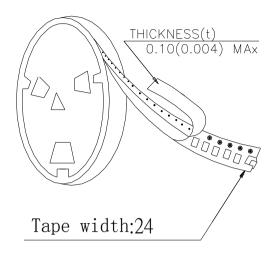
(7)-2 TAPING DIMENSIONS (mm)





(7)-3 REEL DIMENSIONS (mm)





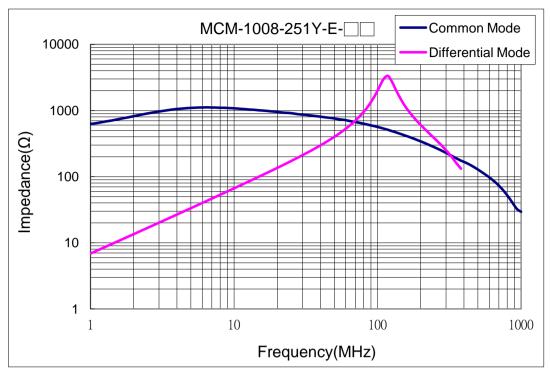
(7)-4 QUANTITY

500 pcs/Reel

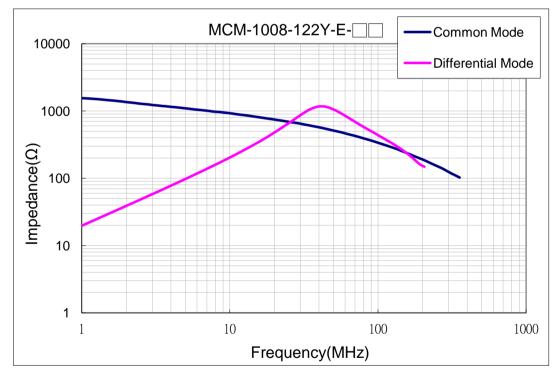
The products are packaged so that no damage will be sustained.

Please note that the contents may change without any prior notice due to reasons such as upgrading.



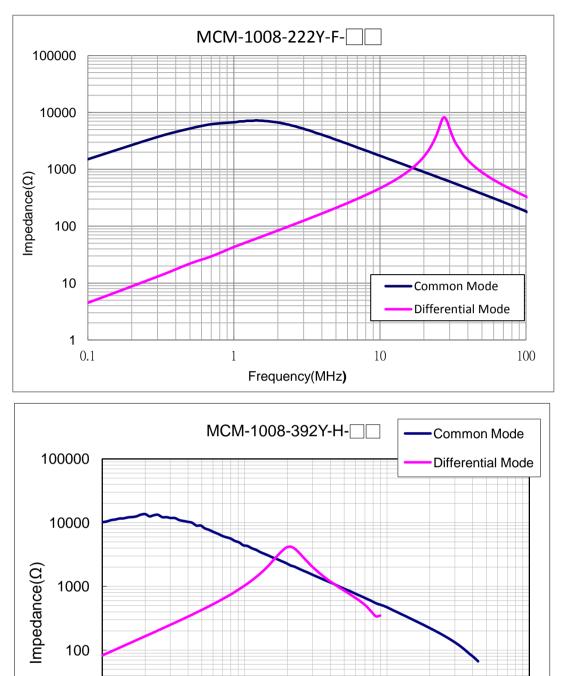


TYPICAL ELECTRICAL CHARACTERISTICS





ATTACHMENT-1



TYPICAL ELECTRICAL CHARACTERISTICS



10

1

1

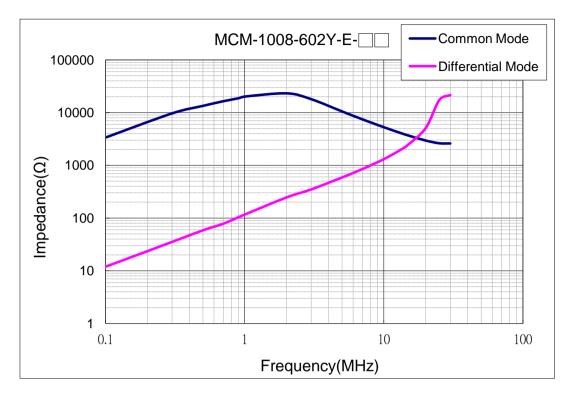
Frequency(MHz)

100

10

ATTACHMENT-2

1000



TYPICAL ELECTRICAL CHARACTERISTICS

